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### What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

### Applications of "[Embedded - Microcontrollers](#)"

#### Details

Product Status	Obsolete
Core Processor	R8C
Core Size	16-Bit
Speed	20MHz
Connectivity	I <sup>2</sup> C, LINbus, SIO, SSU, UART/USART
Peripherals	POR, PWM, Voltage Detect, WDT
Number of I/O	59
Program Memory Size	96KB (96K x 8)
Program Memory Type	FLASH
EEPROM Size	4K x 8
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 5.5V
Data Converters	A/D 12x10b; D/A 2x8b
Oscillator Type	Internal
Operating Temperature	-20°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	64-LQFP
Supplier Device Package	64-LFQFP (10x10)
Purchase URL	<a href="https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f2136acnfp-v0">https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f2136acnfp-v0</a>

**Table 1.2 Specifications for R8C/36C Group (2)**

Item	Function	Specification
Timer	Timer RE	8 bits × 1 Real-time clock mode (count seconds, minutes, hours, days of week), output compare mode
	Timer RF	16 bits × 1 Input capture mode (input capture circuit), output compare mode (output compare circuit)
	Timer RG	16 bits × 1 (with 2 capture/compare registers) Timer mode (input capture function, output compare function), PWM mode (output 1 pin), phase counting mode (available automatic measurement for the counts of 2-phase encoder)
Serial Interface	UART0, UART1	Clock synchronous serial I/O/UART × 2 channel
	UART2	Clock synchronous serial I/O, UART, I <sup>2</sup> C mode (I <sup>2</sup> C bus), multiprocessor communication function
Synchronous Serial Communication Unit (SSU)		1 (shared with I <sup>2</sup> C bus)
I <sup>2</sup> C bus		1 (shared with SSU)
LIN Module		Hardware LIN: 1 (timer RA, UART0)
A/D Converter		10-bit resolution × 12 channels, includes sample and hold function, with sweep mode
D/A Converter		8-bit resolution × 2 circuits
Comparator B		2 circuits
Flash Memory		<ul style="list-style-type: none"> <li>• Programming and erasure voltage: VCC = 2.7 to 5.5 V</li> <li>• Programming and erasure endurance: 10,000 times (data flash) 1,000 times (program ROM)</li> <li>• Program security: ROM code protect, ID code check</li> <li>• Debug functions: On-chip debug, on-board flash rewrite function</li> <li>• Background operation (BGO) function (data flash)</li> </ul>
Operating Frequency/Supply Voltage		f(XIN) = 20 MHz (VCC = 2.7 to 5.5 V) f(XIN) = 5 MHz (VCC = 1.8 to 5.5 V)
Current consumption		Typ. 7.0 mA (VCC = 5.0 V, f(XIN) = 20 MHz) Typ. 3.5 mA (VCC = 3.0 V, f(XIN) = 10 MHz) Typ. 4.0 μA (VCC = 3.0 V, wait mode (f(XCIN) = 32 kHz)) Typ. 2.0 μA (VCC = 3.0 V, stop mode)
Operating Ambient Temperature		−20 to 85°C (N version) −40 to 85°C (D version) <sup>(1)</sup>
Package		64-pin LQFP • Package code: PLQP0064KB-A (previous code: 64P6Q-A) • Package code: PLQP0064GA-A (previous code: 64P6U-A) 64-pin TQFP • Package code: PTQP0064LB-A

Note:

1. Specify the D version if D version functions are to be used.

## 1.2 Product List

Tables 1.3 and 1.4 list Product List for R8C/36C Group. Figure 1.1 shows a Part Number, Memory Size, and Package of R8C/36C Group.

**Table 1.3 Product List for R8C/36C Group (1)**

**Current of Nov 2010**

Part No.	ROM Capacity		RAM Capacity	Package Type	Remarks	
	Program ROM	Data flash				
R5F21364CNFP	16 Kbytes	1 Kbyte × 4	1.5 Kbytes	PLQP0064KB-A	N version	
R5F21365CNFP	24 Kbytes	1 Kbyte × 4	2 Kbytes	PLQP0064KB-A		
R5F21366CNFP	32 Kbytes	1 Kbyte × 4	2.5 Kbytes	PLQP0064KB-A		
R5F21367CNFP	48 Kbytes	1 Kbyte × 4	4 Kbytes	PLQP0064KB-A		
R5F21368CNFP	64 Kbytes	1 Kbyte × 4	6 Kbytes	PLQP0064KB-A		
R5F2136ACNFP	96 Kbytes	1 Kbyte × 4	8 Kbytes	PLQP0064KB-A		
R5F2136CCNFP	128 Kbytes	1 Kbyte × 4	10 Kbytes	PLQP0064KB-A		
R5F21364CNFA	16 Kbytes	1 Kbyte × 4	1.5 Kbytes	PLQP0064GA-A		
R5F21365CNFA	24 Kbytes	1 Kbyte × 4	2 Kbytes	PLQP0064GA-A		
R5F21366CNFA	32 Kbytes	1 Kbyte × 4	2.5 Kbytes	PLQP0064GA-A		
R5F21367CNFA	48 Kbytes	1 Kbyte × 4	4 Kbytes	PLQP0064GA-A		
R5F21368CNFA	64 Kbytes	1 Kbyte × 4	6 Kbytes	PLQP0064GA-A		
R5F2136ACNFA	96 Kbytes	1 Kbyte × 4	8 Kbytes	PLQP0064GA-A		
R5F2136CCNFA	128 Kbytes	1 Kbyte × 4	10 Kbytes	PLQP0064GA-A		
R5F21364CNFB (D)	16 Kbytes	1 Kbyte × 4	1.5 Kbytes	PTQP0064LB-A		
R5F21365CNFB (D)	24 Kbytes	1 Kbyte × 4	2 Kbytes	PTQP0064LB-A		
R5F21366CNFB (D)	32 Kbytes	1 Kbyte × 4	2.5 Kbytes	PTQP0064LB-A		
R5F21367CNFB (D)	48 Kbytes	1 Kbyte × 4	4 Kbytes	PTQP0064LB-A		
R5F21368CNFB (D)	64 Kbytes	1 Kbyte × 4	6 Kbytes	PTQP0064LB-A		
R5F2136ACNFB (D)	96 Kbytes	1 Kbyte × 4	8 Kbytes	PTQP0064LB-A		
R5F2136CCNFB (D)	128 Kbytes	1 Kbyte × 4	10 Kbytes	PTQP0064LB-A		
R5F21364CNXXXFP	16 Kbytes	1 Kbyte × 4	1.5 Kbytes	PLQP0064KB-A	N version	Factory programming product <sup>(1)</sup>
R5F21365CNXXXFP	24 Kbytes	1 Kbyte × 4	2 Kbytes	PLQP0064KB-A		
R5F21366CNXXXFP	32 Kbytes	1 Kbyte × 4	2.5 Kbytes	PLQP0064KB-A		
R5F21367CNXXXFP	48 Kbytes	1 Kbyte × 4	4 Kbytes	PLQP0064KB-A		
R5F21368CNXXXFP	64 Kbytes	1 Kbyte × 4	6 Kbytes	PLQP0064KB-A		
R5F2136ACNXXXFP	96 Kbytes	1 Kbyte × 4	8 Kbytes	PLQP0064KB-A		
R5F2136CCNXXXFP	128 Kbytes	1 Kbyte × 4	10 Kbytes	PLQP0064KB-A		
R5F21364CNXXXFA	16 Kbytes	1 Kbyte × 4	1.5 Kbytes	PLQP0064GA-A		
R5F21365CNXXXFA	24 Kbytes	1 Kbyte × 4	2 Kbytes	PLQP0064GA-A		
R5F21366CNXXXFA	32 Kbytes	1 Kbyte × 4	2.5 Kbytes	PLQP0064GA-A		
R5F21367CNXXXFA	48 Kbytes	1 Kbyte × 4	4 Kbytes	PLQP0064GA-A		
R5F21368CNXXXFA	64 Kbytes	1 Kbyte × 4	6 Kbytes	PLQP0064GA-A		
R5F2136ACNXXXFA	96 Kbytes	1 Kbyte × 4	8 Kbytes	PLQP0064GA-A		
R5F2136CCNXXXFA	128 Kbytes	1 Kbyte × 4	10 Kbytes	PLQP0064GA-A		
R5F21364CNXXXFB (D)	16 Kbytes	1 Kbyte × 4	1.5 Kbytes	PTQP0064LB-A		
R5F21365CNXXXFB (D)	24 Kbytes	1 Kbyte × 4	2 Kbytes	PTQP0064LB-A		
R5F21366CNXXXFB (D)	32 Kbytes	1 Kbyte × 4	2.5 Kbytes	PTQP0064LB-A		
R5F21367CNXXXFB (D)	48 Kbytes	1 Kbyte × 4	4 Kbytes	PTQP0064LB-A		
R5F21368CNXXXFB (D)	64 Kbytes	1 Kbyte × 4	6 Kbytes	PTQP0064LB-A		
R5F2136ACNXXXFB (D)	96 Kbytes	1 Kbyte × 4	8 Kbytes	PTQP0064LB-A		
R5F2136CCNXXXFB (D)	128 Kbytes	1 Kbyte × 4	10 Kbytes	PTQP0064LB-A		

(D): Under development

Note:

1. The user ROM is programmed before shipment.

**Table 1.5 Pin Name Information by Pin Number (1)**

Pin Number	Control Pin	Port	I/O Pin Functions for Peripheral Modules					
			Interrupt	Timer	Serial Interface	SSU	I <sup>2</sup> C bus	A/D Converter, D/A Converter, Comparator B
1		P3_0		(TRA0/TRGCLKA)				
2		P4_2						VREF
3	MODE							
4	(XCIN)	P4_3						
5	(XCOUT)	P4_4						
6	RESET							
7	XOUT	P4_7						
8	VSS/AVSS							
9	XIN	P4_6						
10	VCC/AVCC							
11		P5_4		(TRCIOD)				
12		P5_3		(TRCIOC)				
13		P5_2		(TRCIOB)				
14		P5_1		(TRCIOA/TRCTRG)				
15		P5_0		(TRCCLK)				
16		P3_7		TRA0	(TXD2/SDA2/RXD2/SCL2)	SSO	SDA	
17		P3_5		(TRCIOD)	(CLK2)	SSCK	SCL	
18		P3_4		(TRCIOC)	(TXD2/SDA2/RXD2/SCL2)	SSI		IVREF3
19		P3_3	INT3	(TRCCLK)	(CTS2/RTS2)	SCS		IVCMP3
20		P2_7		(TRDIOD1)				
21		P2_6		(TRDIOC1)				
22		P2_5		(TRDIOB1)				
23		P2_4		(TRDIOA1)				
24		P2_3		(TRDIOD0)				
25		P2_2		(TRCIOD/TRDIOB0)				
26		P2_1		(TRCIOC/TRDIOC0)				
27		P2_0	(INT1)	(TRCIOB/TRDIOA0/TRDCLK)				
28		P3_6	(INT1)					
29		P3_1		(TRBO)				
30		P8_6						
31		P8_5		(TRFO12)				
32		P8_4		(TRFO11)				
33		P8_3		(TRFI/TRFO10)				
34		P8_2		(TRFO02)				
35		P8_1		(TRFO01)				
36		P8_0		(TRFO00)				
37		P6_7	(INT3)	(TRCIOD)				
38		P6_6	INT2	(TRCIOC)	(TXD2/SDA2)			
39		P6_5	INT4	(TRCIOB)	(CLK2/CLK1)			

Note:

1. Can be assigned to the pin in parentheses by a program.

**Table 1.6 Pin Name Information by Pin Number (2)**

Pin Number	Control Pin	Port	I/O Pin Functions for Peripheral Modules					
			Interrupt	Timer	Serial Interface	SSU	I <sup>2</sup> C bus	A/D Converter, D/A Converter, Comparator B
40		P4_5	INT0		(RXD2/SCL2)			ADTRG
41		P1_7	INT1	(TRAIO)				IVCMP1
42		P1_6			(CLK0)			IVREF1
43		P1_5	(INT1)	(TRAIO)	(RXD0)			
44		P1_4		(TRCCLK)	(TXD0)			
45		P1_3	$\overline{\text{KI3}}$	TRBO (/TRCIOB)				AN11
46		P1_2	$\overline{\text{KI2}}$	(TRCIOB)				AN10
47		P1_1	KI1	(TRCIOA/TRCTRG)				AN9
48		P1_0	KI0	(TRCIOD)				AN8
49		P0_7		(TRCIOB)				AN0/DA1
50		P0_6		(TRCIOD)				AN1/DA0
51		P0_5		(TRCIOB)				AN2
52		P0_4		TREO(/TRCIOB)				AN3
53		P0_3		(TRCIOB)	(CLK1)			AN4
54		P0_2		(TRCIOA/TRCTRG)	(RXD1)			AN5
55		P0_1		(TRCIOA/TRCTRG)	(TXD1)			AN6
56		P0_0		(TRCIOA/TRCTRG)				AN7
57		P6_4			(RXD1)			
58		P6_3			(TXD1)			
59		P6_2			(CLK1)			
60		P6_1						
61		P6_0		(TREO)				
62		P5_7		(TRGIOB)				
63		P5_6		(TRAO/TRGIOA)				
64		P3_2	(INT1/ INT2)	(TRAIO/TRGCLKB)				

Note:

1. Can be assigned to the pin in parentheses by a program.

## 2.1 Data Registers (R0, R1, R2, and R3)

R0 is a 16-bit register for transfer, arithmetic, and logic operations. The same applies to R1 to R3. R0 can be split into high-order bits (R0H) and low-order bits (R0L) to be used separately as 8-bit data registers. R1H and R1L are analogous to R0H and R0L. R2 can be combined with R0 and used as a 32-bit data register (R2R0). R3R1 is analogous to R2R0.

## 2.2 Address Registers (A0 and A1)

A0 is a 16-bit register for address register indirect addressing and address register relative addressing. It is also used for transfer, arithmetic, and logic operations. A1 is analogous to A0. A1 can be combined with A0 and as a 32-bit address register (A1A0).

## 2.3 Frame Base Register (FB)

FB is a 16-bit register for FB relative addressing.

## 2.4 Interrupt Table Register (INTB)

INTB is a 20-bit register that indicates the starting address of an interrupt vector table.

## 2.5 Program Counter (PC)

PC is 20 bits wide and indicates the address of the next instruction to be executed.

## 2.6 User Stack Pointer (USP) and Interrupt Stack Pointer (ISP)

The stack pointers (SP), USP and ISP, are each 16 bits wide. The U flag of FLG is used to switch between USP and ISP.

## 2.7 Static Base Register (SB)

SB is a 16-bit register for SB relative addressing.

## 2.8 Flag Register (FLG)

FLG is an 11-bit register indicating the CPU state.

### 2.8.1 Carry Flag (C)

The C flag retains carry, borrow, or shift-out bits that have been generated by the arithmetic and logic unit.

### 2.8.2 Debug Flag (D)

The D flag is for debugging only. Set it to 0.

### 2.8.3 Zero Flag (Z)

The Z flag is set to 1 when an arithmetic operation results in 0; otherwise to 0.

### 2.8.4 Sign Flag (S)

The S flag is set to 1 when an arithmetic operation results in a negative value; otherwise to 0.

### 2.8.5 Register Bank Select Flag (B)

Register bank 0 is selected when the B flag is 0. Register bank 1 is selected when this flag is set to 1.

### 2.8.6 Overflow Flag (O)

The O flag is set to 1 when an operation results in an overflow; otherwise to 0.

### 2.8.7 Interrupt Enable Flag (I)

The I flag enables maskable interrupts.

Interrupts are disabled when the I flag is set to 0, and are enabled when the I flag is set to 1. The I flag is set to 0 when an interrupt request is acknowledged.

### 2.8.8 Stack Pointer Select Flag (U)

ISP is selected when the U flag is set to 0; USP is selected when the U flag is set to 1.

The U flag is set to 0 when a hardware interrupt request is acknowledged or the INT instruction of software interrupt numbers 0 to 31 is executed.

### 2.8.9 Processor Interrupt Priority Level (IPL)

IPL is 3 bits wide and assigns processor interrupt priority levels from level 0 to level 7.

If a requested interrupt has higher priority than IPL, the interrupt is enabled.

### 2.8.10 Reserved Bit

If necessary, set to 0. When read, the content is undefined.

## 4. Special Function Registers (SFRs)

An SFR (special function register) is a control register for a peripheral function. Tables 4.1 to 4.12 list the special function registers. Table 4.13 lists the ID Code Areas and Option Function Select Area.

**Table 4.1 SFR Information (1) (1)**

Address	Register	Symbol	After Reset
0000h			
0001h			
0002h			
0003h			
0004h	Processor Mode Register 0	PM0	00h
0005h	Processor Mode Register 1	PM1	00h
0006h	System Clock Control Register 0	CM0	00101000b
0007h	System Clock Control Register 1	CM1	00100000b
0008h	Module Standby Control Register	MSTCR	00h
0009h	System Clock Control Register 3	CM3	00h
000Ah	Protect Register	PRCR	00h
000Bh	Reset Source Determination Register	RSTFR	0XXXXXXb (2)
000Ch	Oscillation Stop Detection Register	OCD	00000100b
000Dh	Watchdog Timer Reset Register	WDTR	XXh
000Eh	Watchdog Timer Start Register	WDTs	XXh
000Fh	Watchdog Timer Control Register	WDTC	00111111b
0010h			
0011h			
0012h			
0013h			
0014h			
0015h	High-Speed On-Chip Oscillator Control Register 7	FRA7	When shipping
0016h			
0017h			
0018h			
0019h			
001Ah			
001Bh			
001Ch	Count Source Protection Mode Register	CSPR	00h 10000000b (3)
001Dh			
001Eh			
001Fh			
0020h			
0021h			
0022h			
0023h	High-Speed On-Chip Oscillator Control Register 0	FRA0	00h
0024h	High-Speed On-Chip Oscillator Control Register 1	FRA1	When shipping
0025h	High-Speed On-Chip Oscillator Control Register 2	FRA2	00h
0026h	On-Chip Reference Voltage Control Register	OCVREFCR	00h
0027h			
0028h	Clock Prescaler Reset Flag	CPSRF	00h
0029h	High-Speed On-Chip Oscillator Control Register 4	FRA4	When shipping
002Ah	High-Speed On-Chip Oscillator Control Register 5	FRA5	When shipping
002Bh	High-Speed On-Chip Oscillator Control Register 6	FRA6	When shipping
002Ch			
002Dh			
002Eh			
002Fh	High-Speed On-Chip Oscillator Control Register 3	FRA3	When shipping
0030h	Voltage Monitor Circuit Control Register	CMPA	00h
0031h	Voltage Monitor Circuit Edge Select Register	VCAC	00h
0032h			
0033h	Voltage Detect Register 1	VCA1	00001000b
0034h	Voltage Detect Register 2	VCA2	00h (4) 00100000b (5)
0035h			
0036h	Voltage Detection 1 Level Select Register	VD1LS	00000111b
0037h			
0038h	Voltage Monitor 0 Circuit Control Register	VW0C	1100X010b (4) 1100X011b (5)
0039h	Voltage Monitor 1 Circuit Control Register	VW1C	10001010b

X: Undefined

Notes:

1. The blank areas are reserved and cannot be accessed by users.
2. The CWR bit in the RSTFR register is set to 0 after power-on and voltage monitor 0 reset. Hardware reset, software reset, or watchdog timer reset does not affect this bit.
3. The CSPROINI bit in the OFS register is set to 0.
4. The LVDAS bit in the OFS register is set to 1.
5. The LVDAS bit in the OFS register is set to 0.



**Table 4.4      SFR Information (4) <sup>(1)</sup>**

Address	Register	Symbol	After Reset
00C0h	A/D Register 0	AD0	XXh
00C1h			000000XXb
00C2h	A/D Register 1	AD1	XXh
00C3h			000000XXb
00C4h	A/D Register 2	AD2	XXh
00C5h			000000XXb
00C6h	A/D Register 3	AD3	XXh
00C7h			000000XXb
00C8h	A/D Register 4	AD4	XXh
00C9h			000000XXb
00CAh	A/D Register 5	AD5	XXh
00CBh			000000XXb
00CCh	A/D Register 6	AD6	XXh
00CDh			000000XXb
00CEh	A/D Register 7	AD7	XXh
00CFh			000000XXb
00D0h			
00D1h			
00D2h			
00D3h			
00D4h	A/D Mode Register	ADMOD	00h
00D5h	A/D Input Select Register	ADINSEL	11000000b
00D6h	A/D Control Register 0	ADCON0	00h
00D7h	A/D Control Register 1	ADCON1	00h
00D8h	D/A0 Register	DA0	00h
00D9h	D/A1 Register	DA1	00h
00DAh			
00DBh			
00DCh	D/A Control Register	DACON	00h
00DDh			
00DEh			
00DFh			
00E0h	Port P0 Register	P0	XXh
00E1h	Port P1 Register	P1	XXh
00E2h	Port P0 Direction Register	PD0	00h
00E3h	Port P1 Direction Register	PD1	00h
00E4h	Port P2 Register	P2	XXh
00E5h	Port P3 Register	P3	XXh
00E6h	Port P2 Direction Register	PD2	00h
00E7h	Port P3 Direction Register	PD3	00h
00E8h	Port P4 Register	P4	XXh
00E9h	Port P5 Register	P5	XXh
00EAh	Port P4 Direction Register	PD4	00h
00EBh	Port P5 Direction Register	PD5	00h
00ECh	Port P6 Register	P6	XXh
00EDh			
00EEh	Port P6 Direction Register	PD6	00h
00EFh			
00F0h	Port P8 Register	P8	XXh
00F1h			
00F2h	Port P8 Direction Register	PD8	00h
00F3h			
00F4h			
00F5h			
00F6h			
00F7h			
00F8h			
00F9h			
00FAh			
00FBh			
00FCh			
00FDh			
00FEh			
00FFh			

X: Undefined

Note:

1. The blank areas are reserved and cannot be accessed by users.

**Table 4.11 SFR Information (11) (1)**

Address	Register	Symbol	After Reset
2CB0h	DTC Control Data 14	DTCD14	XXh
2CB1h			XXh
2CB2h			XXh
2CB3h			XXh
2CB4h			XXh
2CB5h			XXh
2CB6h			XXh
2CB7h			XXh
2CB8h	DTC Control Data 15	DTCD15	XXh
2CB9h			XXh
2CBAh			XXh
2CBBh			XXh
2CBCh			XXh
2CBDh			XXh
2CBEh			XXh
2CBFh			XXh
2CC0h	DTC Control Data 16	DTCD16	XXh
2CC1h			XXh
2CC2h			XXh
2CC3h			XXh
2CC4h			XXh
2CC5h			XXh
2CC6h			XXh
2CC7h			XXh
2CC8h	DTC Control Data 17	DTCD17	XXh
2CC9h			XXh
2CCAh			XXh
2CCBh			XXh
2CCCh			XXh
2CCDh			XXh
2CCEh			XXh
2CCFh			XXh
2CD0h	DTC Control Data 18	DTCD18	XXh
2CD1h			XXh
2CD2h			XXh
2CD3h			XXh
2CD4h			XXh
2CD5h			XXh
2CD6h			XXh
2CD7h			XXh
2CD8h	DTC Control Data 19	DTCD19	XXh
2CD9h			XXh
2CDAh			XXh
2CDBh			XXh
2CDCh			XXh
2CDDh			XXh
2CDEh			XXh
2CDFh			XXh
2CE0h	DTC Control Data 20	DTCD20	XXh
2CE1h			XXh
2CE2h			XXh
2CE3h			XXh
2CE4h			XXh
2CE5h			XXh
2CE6h			XXh
2CE7h			XXh
2CE8h	DTC Control Data 21	DTCD21	XXh
2CE9h			XXh
2CEAh			XXh
2CEBh			XXh
2CECh			XXh
2CEDh			XXh
2CEEh			XXh
2CEFh			XXh

X: Undefined

Note:

1. The blank areas are reserved and cannot be accessed by users.

**Table 5.2 Recommended Operating Conditions (1)**

Symbol	Parameter				Conditions	Standard			Unit
						Min.	Typ.	Max.	
V <sub>CC</sub> /AV <sub>CC</sub>	Supply voltage					1.8	—	5.5	V
V <sub>SS</sub> /AV <sub>SS</sub>	Supply voltage					—	0	—	V
V <sub>IH</sub>	Input “H” voltage	Other than CMOS input				0.8 V <sub>CC</sub>	—	V <sub>CC</sub>	V
		CMOS input	Input level switching function (I/O port)	Input level selection: 0.35 V <sub>CC</sub>	4.0 V ≤ V <sub>CC</sub> ≤ 5.5 V	0.5 V <sub>CC</sub>	—	V <sub>CC</sub>	V
					2.7 V ≤ V <sub>CC</sub> < 4.0 V	0.55 V <sub>CC</sub>	—	V <sub>CC</sub>	V
					1.8 V ≤ V <sub>CC</sub> < 2.7 V	0.65 V <sub>CC</sub>	—	V <sub>CC</sub>	V
				Input level selection: 0.5 V <sub>CC</sub>	4.0 V ≤ V <sub>CC</sub> ≤ 5.5 V	0.65 V <sub>CC</sub>	—	V <sub>CC</sub>	V
				2.7 V ≤ V <sub>CC</sub> < 4.0 V	0.7 V <sub>CC</sub>	—	V <sub>CC</sub>	V	
				1.8 V ≤ V <sub>CC</sub> < 2.7 V	0.8 V <sub>CC</sub>	—	V <sub>CC</sub>	V	
				Input level selection: 0.7 V <sub>CC</sub>	4.0 V ≤ V <sub>CC</sub> ≤ 5.5 V	0.85 V <sub>CC</sub>	—	V <sub>CC</sub>	V
				2.7 V ≤ V <sub>CC</sub> < 4.0 V	0.85 V <sub>CC</sub>	—	V <sub>CC</sub>	V	
				1.8 V ≤ V <sub>CC</sub> < 2.7 V	0.85 V <sub>CC</sub>	—	V <sub>CC</sub>	V	
		External clock input (XOUT)				1.2	—	V <sub>CC</sub>	V
V <sub>IL</sub>	Input “L” voltage	Other than CMOS input				0	—	0.2 V <sub>CC</sub>	V
		CMOS input	Input level switching function (I/O port)	Input level selection: 0.35 V <sub>CC</sub>	4.0 V ≤ V <sub>CC</sub> ≤ 5.5 V	0	—	0.2 V <sub>CC</sub>	V
					2.7 V ≤ V <sub>CC</sub> < 4.0 V	0	—	0.2 V <sub>CC</sub>	V
					1.8 V ≤ V <sub>CC</sub> < 2.7 V	0	—	0.2 V <sub>CC</sub>	V
				Input level selection: 0.5 V <sub>CC</sub>	4.0 V ≤ V <sub>CC</sub> ≤ 5.5 V	0	—	0.4 V <sub>CC</sub>	V
				2.7 V ≤ V <sub>CC</sub> < 4.0 V	0	—	0.3 V <sub>CC</sub>	V	
				1.8 V ≤ V <sub>CC</sub> < 2.7 V	0	—	0.2 V <sub>CC</sub>	V	
				Input level selection: 0.7 V <sub>CC</sub>	4.0 V ≤ V <sub>CC</sub> ≤ 5.5 V	0	—	0.55 V <sub>CC</sub>	V
				2.7 V ≤ V <sub>CC</sub> < 4.0 V	0	—	0.45 V <sub>CC</sub>	V	
				1.8 V ≤ V <sub>CC</sub> < 2.7 V	0	—	0.35 V <sub>CC</sub>	V	
		External clock input (XOUT)				0	—	0.4	V
I <sub>OH</sub> (sum)	Peak sum output “H” current	Sum of all pins I <sub>OH</sub> (peak)		—	—	−160	mA		
I <sub>OH</sub> (sum)	Average sum output “H” current	Sum of all pins I <sub>OH</sub> (avg)		—	—	−80	mA		
I <sub>OH</sub> (peak)	Peak output “H” current	Drive capacity Low		—	—	−10	mA		
		Drive capacity High		—	—	−40	mA		
I <sub>OH</sub> (avg)	Average output “H” current	Drive capacity Low		—	—	−5	mA		
		Drive capacity High		—	—	−20	mA		
I <sub>OL</sub> (sum)	Peak sum output “L” current	Sum of all pins I <sub>OL</sub> (peak)		—	—	160	mA		
I <sub>OL</sub> (sum)	Average sum output “L” current	Sum of all pins I <sub>OL</sub> (avg)		—	—	80	mA		
I <sub>OL</sub> (peak)	Peak output “L” current	Drive capacity Low		—	—	10	mA		
		Drive capacity High		—	—	40	mA		
I <sub>OL</sub> (avg)	Average output “L” current	Drive capacity Low		—	—	5	mA		
		Drive capacity High		—	—	20	mA		
f <sub>(XIN)</sub>	XIN clock input oscillation frequency			2.7 V ≤ V <sub>CC</sub> ≤ 5.5 V	—	—	20	MHz	
				1.8 V ≤ V <sub>CC</sub> < 2.7 V	—	—	5	MHz	
f <sub>(XCIN)</sub>	XCIN clock input oscillation frequency			1.8 V ≤ V <sub>CC</sub> ≤ 5.5 V	—	32.768	50	kHz	
f <sub>OCO40M</sub>	When used as the count source for timer RC, timer RD or timer RG <sup>(3)</sup>			2.7 V ≤ V <sub>CC</sub> ≤ 5.5 V	32	—	40	MHz	
f <sub>OCO-F</sub>	f <sub>OCO-F</sub> frequency			2.7 V ≤ V <sub>CC</sub> ≤ 5.5 V	—	—	20	MHz	
				1.8 V ≤ V <sub>CC</sub> < 2.7 V	—	—	5	MHz	
—	System clock frequency			2.7 V ≤ V <sub>CC</sub> ≤ 5.5 V	—	—	20	MHz	
				1.8 V ≤ V <sub>CC</sub> < 2.7 V	—	—	5	MHz	
f <sub>(BCLK)</sub>	CPU clock frequency			2.7 V ≤ V <sub>CC</sub> ≤ 5.5 V	—	—	20	MHz	
				1.8 V ≤ V <sub>CC</sub> < 2.7 V	—	—	5	MHz	

**Notes:**

1. V<sub>CC</sub> = 1.8 to 5.5 V and T<sub>opr</sub> = −20 to 85 °C (N version)/−40 to 85 °C (D version), unless otherwise specified.
2. The average output current indicates the average value of current measured during 100 ms.
3. f<sub>OCO40M</sub> can be used as the count source for timer RC, timer RD or timer RG in the range of V<sub>CC</sub> = 2.7 to 5.5 V.

**Table 5.8 Voltage Detection 0 Circuit Electrical Characteristics**

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
Vdet0	Voltage detection level Vdet0_0 <sup>(2)</sup>		1.80	1.90	2.05	V
	Voltage detection level Vdet0_1 <sup>(2)</sup>		2.15	2.35	2.50	V
	Voltage detection level Vdet0_2 <sup>(2)</sup>		2.70	2.85	3.05	V
	Voltage detection level Vdet0_3 <sup>(2)</sup>		3.55	3.80	4.05	V
—	Voltage detection 0 circuit response time <sup>(4)</sup>	At the falling of Vcc from 5.0 V to (Vdet0_0 – 0.1) V	—	6	150	μs
—	Voltage detection circuit self power consumption	VCA25 = 1, Vcc = 5.0 V	—	1.5	—	μA
td(E-A)	Waiting time until voltage detection circuit operation starts <sup>(3)</sup>		—	—	100	μs

Notes:

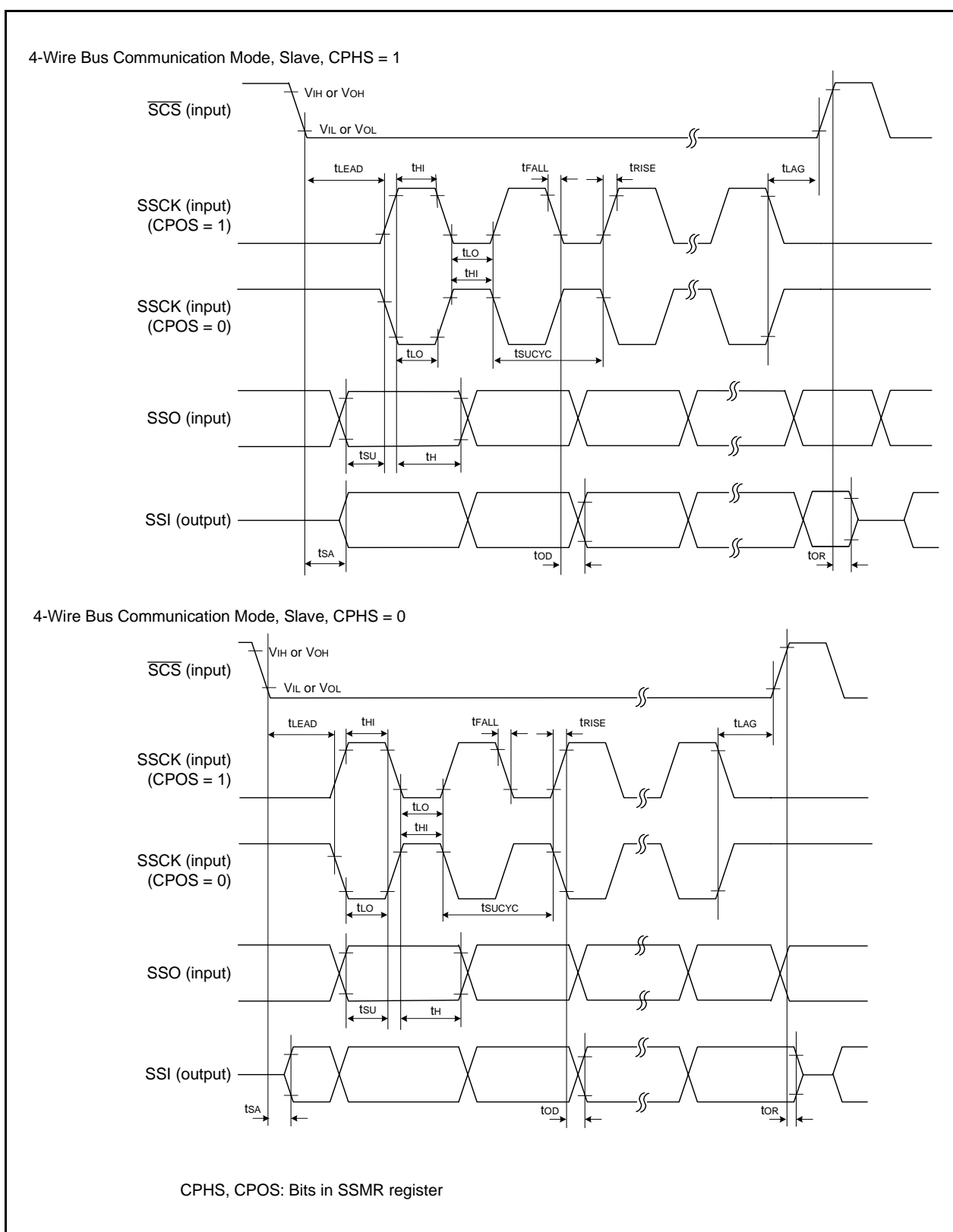
1. The measurement condition is Vcc = 1.8 to 5.5 V and T<sub>opr</sub> = –20 to 85 °C (N version)/–40 to 85 °C (D version).
2. Select the voltage detection level with bits VDSEL0 and VDSEL1 in the OFS register.
3. Necessary time until the voltage detection circuit operates when setting to 1 again after setting the VCA2 bit in the VCA2 register to 0.
4. Time until the voltage monitor 0 reset is generated after the voltage passes Vdet0.

**Table 5.9 Voltage Detection 1 Circuit Electrical Characteristics**

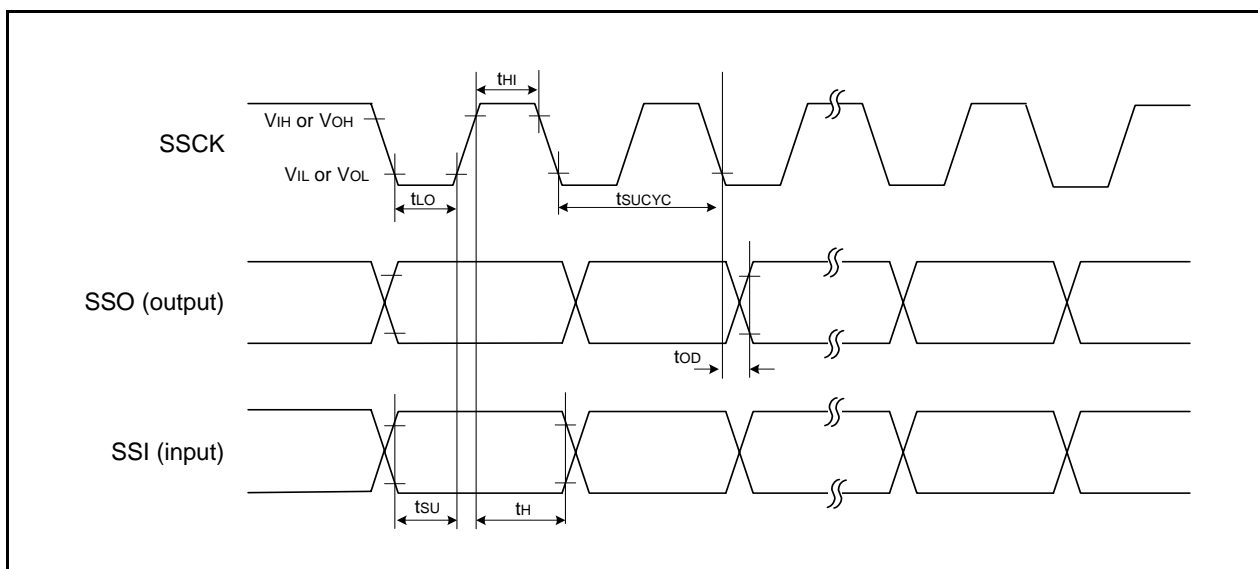
Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
Vdet1	Voltage detection level Vdet1_0 <sup>(2)</sup>	At the falling of Vcc	2.00	2.20	2.40	V
	Voltage detection level Vdet1_1 <sup>(2)</sup>	At the falling of Vcc	2.15	2.35	2.55	V
	Voltage detection level Vdet1_2 <sup>(2)</sup>	At the falling of Vcc	2.30	2.50	2.70	V
	Voltage detection level Vdet1_3 <sup>(2)</sup>	At the falling of Vcc	2.45	2.65	2.85	V
	Voltage detection level Vdet1_4 <sup>(2)</sup>	At the falling of Vcc	2.60	2.80	3.00	V
	Voltage detection level Vdet1_5 <sup>(2)</sup>	At the falling of Vcc	2.75	2.95	3.15	V
	Voltage detection level Vdet1_6 <sup>(2)</sup>	At the falling of Vcc	2.85	3.10	3.40	V
	Voltage detection level Vdet1_7 <sup>(2)</sup>	At the falling of Vcc	3.00	3.25	3.55	V
	Voltage detection level Vdet1_8 <sup>(2)</sup>	At the falling of Vcc	3.15	3.40	3.70	V
	Voltage detection level Vdet1_9 <sup>(2)</sup>	At the falling of Vcc	3.30	3.55	3.85	V
	Voltage detection level Vdet1_A <sup>(2)</sup>	At the falling of Vcc	3.45	3.70	4.00	V
	Voltage detection level Vdet1_B <sup>(2)</sup>	At the falling of Vcc	3.60	3.85	4.15	V
	Voltage detection level Vdet1_C <sup>(2)</sup>	At the falling of Vcc	3.75	4.00	4.30	V
	Voltage detection level Vdet1_D <sup>(2)</sup>	At the falling of Vcc	3.90	4.15	4.45	V
	Voltage detection level Vdet1_E <sup>(2)</sup>	At the falling of Vcc	4.05	4.30	4.60	V
	Voltage detection level Vdet1_F <sup>(2)</sup>	At the falling of Vcc	4.20	4.45	4.75	V
—	Hysteresis width at the rising of Vcc in voltage detection 1 circuit	Vdet1_0 to Vdet1_5 selected	—	0.07	—	V
		Vdet1_6 to Vdet1_F selected	—	0.10	—	V
—	Voltage detection 1 circuit response time <sup>(3)</sup>	At the falling of Vcc from 5.0 V to (Vdet1_0 – 0.1) V	—	60	150	μs
—	Voltage detection circuit self power consumption	VCA26 = 1, Vcc = 5.0 V	—	1.7	—	μA
td(E-A)	Waiting time until voltage detection circuit operation starts <sup>(4)</sup>		—	—	100	μs

Notes:

1. The measurement condition is Vcc = 1.8 to 5.5 V and T<sub>opr</sub> = –20 to 85 °C (N version)/–40 to 85 °C (D version).
2. Select the voltage detection level with bits VD1S0 to VD1S3 in the VD1LS register.
3. Time until the voltage monitor 1 interrupt request is generated after the voltage passes Vdet1.
4. Necessary time until the voltage detection circuit operates when setting to 1 again after setting the VCA26 bit in the VCA2 register to 0.



**Figure 5.5 I/O Timing of Synchronous Serial Communication Unit (SSU) (Slave)**



**Figure 5.6 I/O Timing of Synchronous Serial Communication Unit (SSU) (Clock Synchronous Communication Mode)**

**Table 5.24 Electrical Characteristics (3) [ $2.7\text{ V} \leq V_{CC} < 4.2\text{ V}$ ]**

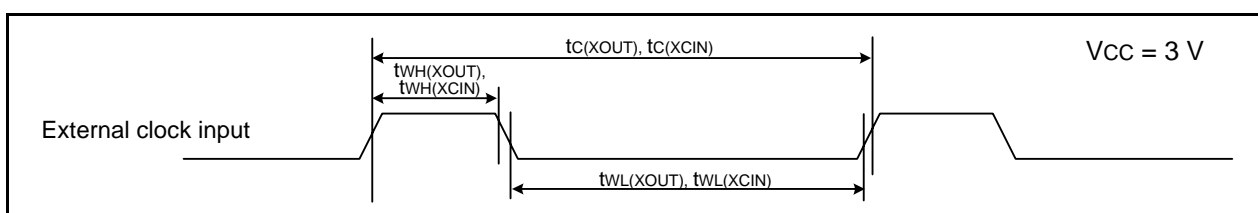
Symbol	Parameter		Condition		Standard			Unit
					Min.	Typ.	Max.	
V <sub>OH</sub>	Output "H" voltage	Other than XOUT	Drive capacity High	I <sub>OH</sub> = -5 mA	V <sub>CC</sub> - 0.5	—	V <sub>CC</sub>	V
			Drive capacity Low	I <sub>OH</sub> = -1 mA	V <sub>CC</sub> - 0.5	—	V <sub>CC</sub>	V
		XOUT		I <sub>OH</sub> = -200 $\mu$ A	1.0	—	V <sub>CC</sub>	V
V <sub>OL</sub>	Output "L" voltage	Other than XOUT	Drive capacity High	I <sub>OL</sub> = 5 mA	—	—	0.5	V
			Drive capacity Low	I <sub>OL</sub> = 1 mA	—	—	0.5	V
		XOUT		I <sub>OL</sub> = 200 $\mu$ A	—	—	0.5	V
V <sub>T+</sub> -V <sub>T-</sub>	Hysteresis	INT0, INT1, INT2, INT3, INT4, KI0, KI1, KI2, KI3, TRAIO, TRBO, TRCIOA, TRCIOB, TRCIOC, TRCIOD, TRDIOA0, TRDIOB0, TRDIOC0, TRDIOD0, TRDIOA1, TRDIOB1, TRDIOC1, TRDIOD1, TRCTRG, TRCCLK, TRFI, TRGIOA, TRGIOB, ADTRG, RXD0, RXD1, RXD2, CLK0, CLK1, CLK2, SSI, SCL, SDA, SSO	V <sub>CC</sub> = 3.0 V		0.1	0.4	—	V
		RESET	V <sub>CC</sub> = 3.0 V		0.1	0.5	—	V
I <sub>IH</sub>	Input "H" current		V <sub>I</sub> = 3 V, V <sub>CC</sub> = 3.0 V		—	—	4.0	$\mu$ A
I <sub>IL</sub>	Input "L" current		V <sub>I</sub> = 0 V, V <sub>CC</sub> = 3.0 V		—	—	-4.0	$\mu$ A
R <sub>PULLUP</sub>	Pull-up resistance		V <sub>I</sub> = 0 V, V <sub>CC</sub> = 3.0 V		42	84	168	k $\Omega$
R <sub>fXIN</sub>	Feedback resistance	XIN			—	0.3	—	M $\Omega$
R <sub>fXCIN</sub>	Feedback resistance	XCIN			—	8	—	M $\Omega$
V <sub>RAM</sub>	RAM hold voltage		During stop mode		1.8	—	—	V

Note:

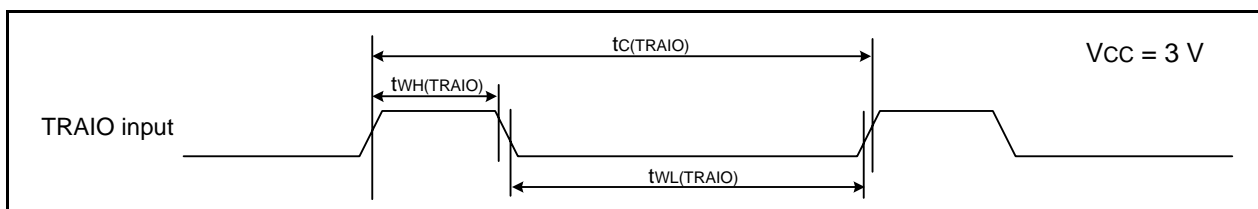
1.  $2.7\text{ V} \leq V_{CC} < 4.2\text{ V}$ , T<sub>opr</sub> = -20 to 85 °C (N version)/-40 to 85 °C (D version), and f(XIN) = 10 MHz, unless otherwise specified.

**Timing requirements** (Unless Otherwise Specified:  $V_{CC} = 3\text{ V}$ ,  $V_{SS} = 0\text{ V}$ ,  $T_{opr} = 25\text{ }^{\circ}\text{C}$ )**Table 5.26 External Clock Input (XOUT, XCIN)**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_c(\text{XOUT})$	XOUT input cycle time	50	—	ns
$t_{WH}(\text{XOUT})$	XOUT input "H" width	24	—	ns
$t_{WL}(\text{XOUT})$	XOUT input "L" width	24	—	ns
$t_c(\text{XCIN})$	XCIN input cycle time	14	—	$\mu\text{s}$
$t_{WH}(\text{XCIN})$	XCIN input "H" width	7	—	$\mu\text{s}$
$t_{WL}(\text{XCIN})$	XCIN input "L" width	7	—	$\mu\text{s}$

**Figure 5.13 External Clock Input Timing Diagram when  $V_{CC} = 3\text{ V}$** **Table 5.27 TRAIO Input**

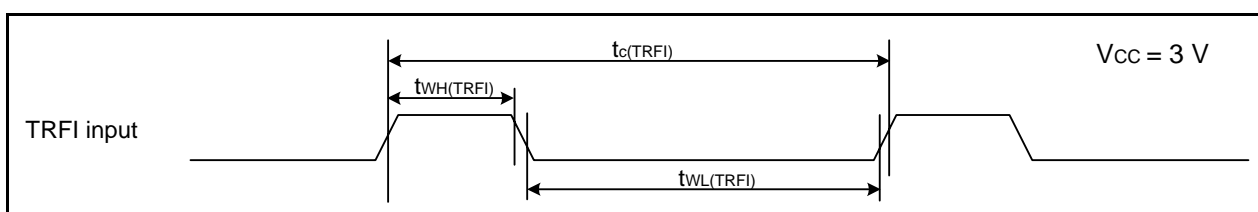
Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_c(\text{TRAIO})$	TRAIO input cycle time	300	—	ns
$t_{WH}(\text{TRAIO})$	TRAIO input "H" width	120	—	ns
$t_{WL}(\text{TRAIO})$	TRAIO input "L" width	120	—	ns

**Figure 5.14 TRAIO Input Timing Diagram when  $V_{CC} = 3\text{ V}$** **Table 5.28 TRFI Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_c(\text{TRFI})$	TRFI input cycle time	1200 (1)	—	ns
$t_{WH}(\text{TRFI})$	TRFI input "H" width	600 (2)	—	ns
$t_{WL}(\text{TRFI})$	TRFI input "L" width	600 (2)	—	ns

**Notes:**

1. When using timer RF input capture mode, adjust the cycle time to  $(1/\text{timer RF count source frequency} \times 3)$  or above.
2. When using timer RF input capture mode, adjust the pulse width to  $(1/\text{timer RF count source frequency} \times 1.5)$  or above.

**Figure 5.15 TRFI Input Timing Diagram when  $V_{CC} = 3\text{ V}$**



**Table 5.31 Electrical Characteristics (5) [ $1.8\text{ V} \leq V_{CC} < 2.7\text{ V}$ ]**

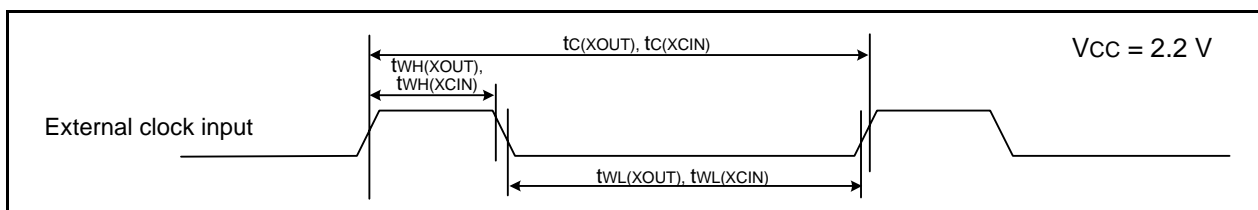
Symbol	Parameter		Condition		Standard			Unit
					Min.	Typ.	Max.	
V <sub>OH</sub>	Output "H" voltage	Other than XOUT	Drive capacity High	I <sub>OH</sub> = -2 mA	V <sub>CC</sub> - 0.5	—	V <sub>CC</sub>	V
			Drive capacity Low	I <sub>OH</sub> = -1 mA	V <sub>CC</sub> - 0.5	—	V <sub>CC</sub>	V
		XOUT		I <sub>OH</sub> = -200 $\mu$ A	1.0	—	V <sub>CC</sub>	V
V <sub>OL</sub>	Output "L" voltage	Other than XOUT	Drive capacity High	I <sub>OL</sub> = 2 mA	—	—	0.5	V
			Drive capacity Low	I <sub>OL</sub> = 1 mA	—	—	0.5	V
		XOUT		I <sub>OL</sub> = 200 $\mu$ A	—	—	0.5	V
V <sub>T+</sub> -V <sub>T-</sub>	Hysteresis	NT0, INT1, INT2, INT3, INT4, KI0, KI1, KI2, KI3, TRAIO, TRBO, TRCIOA, TRCIOB, TRCIOC, TRCIOD, TRDIOA0, TRDIOB0, TRDIOC0, TRDIOD0, TRDIOA1, TRDIOB1, TRDIOC1, TRDIOD1, TRCTRG, TRCCLK, TRFI, TRGIOA, TRGIOB, ADTRG, RXD0, RXD1, RXD2, CLK0, CLK1, CLK2, SSI, SCL, SDA, SSO			0.05	0.20	—	V
		RESET			0.05	0.20	—	V
I <sub>IH</sub>	Input "H" current		V <sub>I</sub> = 2.2 V, V <sub>CC</sub> = 2.2 V		—	—	4.0	$\mu$ A
I <sub>IL</sub>	Input "L" current		V <sub>I</sub> = 0 V, V <sub>CC</sub> = 2.2 V		—	—	-4.0	$\mu$ A
R <sub>PULLUP</sub>	Pull-up resistance		V <sub>I</sub> = 0 V, V <sub>CC</sub> = 2.2 V		70	140	300	k $\Omega$
R <sub>fXIN</sub>	Feedback resistance	XIN			—	0.3	—	M $\Omega$
R <sub>fXCIN</sub>	Feedback resistance	XCIN			—	8	—	M $\Omega$
V <sub>RAM</sub>	RAM hold voltage		During stop mode		1.8	—	—	V

Note:

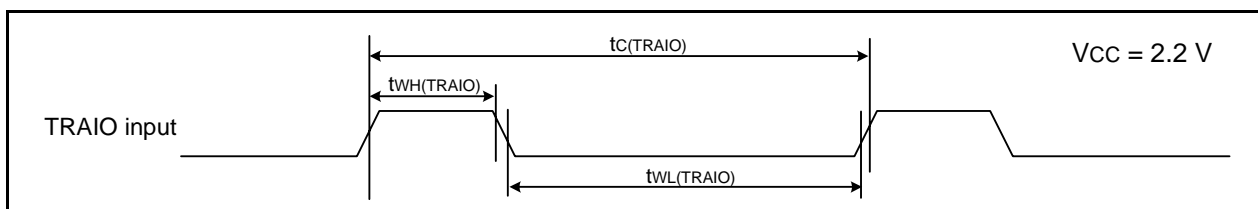
1.  $1.8\text{ V} \leq V_{CC} < 2.7\text{ V}$ , T<sub>opr</sub> = -20 to 85 °C (N version)/-40 to 85 °C (D version), and f(XIN) = 5 MHz, unless otherwise specified.

**Timing requirements** (Unless Otherwise Specified:  $V_{CC} = 2.2\text{ V}$ ,  $V_{SS} = 0\text{ V}$ ,  $T_{opr} = 25\text{ }^{\circ}\text{C}$ )**Table 5.33 External Clock Input (XOUT, XCIN)**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_c(\text{XOUT})$	XOUT input cycle time	200	—	ns
$t_{WH}(\text{XOUT})$	XOUT input "H" width	90	—	ns
$t_{WL}(\text{XOUT})$	XOUT input "L" width	90	—	ns
$t_c(\text{XCIN})$	XCIN input cycle time	14	—	$\mu\text{s}$
$t_{WH}(\text{XCIN})$	XCIN input "H" width	7	—	$\mu\text{s}$
$t_{WL}(\text{XCIN})$	XCIN input "L" width	7	—	$\mu\text{s}$

**Figure 5.18 External Clock Input Timing Diagram when  $V_{CC} = 2.2\text{ V}$** **Table 5.34 TRAIO Input**

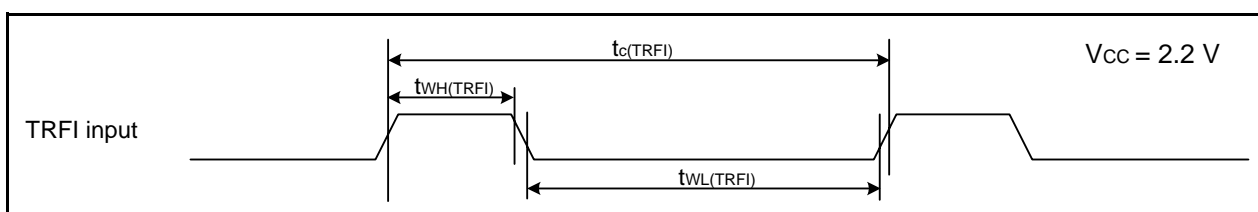
Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_c(\text{TRAIO})$	TRAIO input cycle time	500	—	ns
$t_{WH}(\text{TRAIO})$	TRAIO input "H" width	200	—	ns
$t_{WL}(\text{TRAIO})$	TRAIO input "L" width	200	—	ns

**Figure 5.19 TRAIO Input Timing Diagram when  $V_{CC} = 2.2\text{ V}$** **Table 5.35 TRFI Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_c(\text{TRFI})$	TRFI input cycle time	2000 (1)	—	ns
$t_{WH}(\text{TRFI})$	TRFI input "H" width	1000 (2)	—	ns
$t_{WL}(\text{TRFI})$	TRFI input "L" width	1000 (2)	—	ns

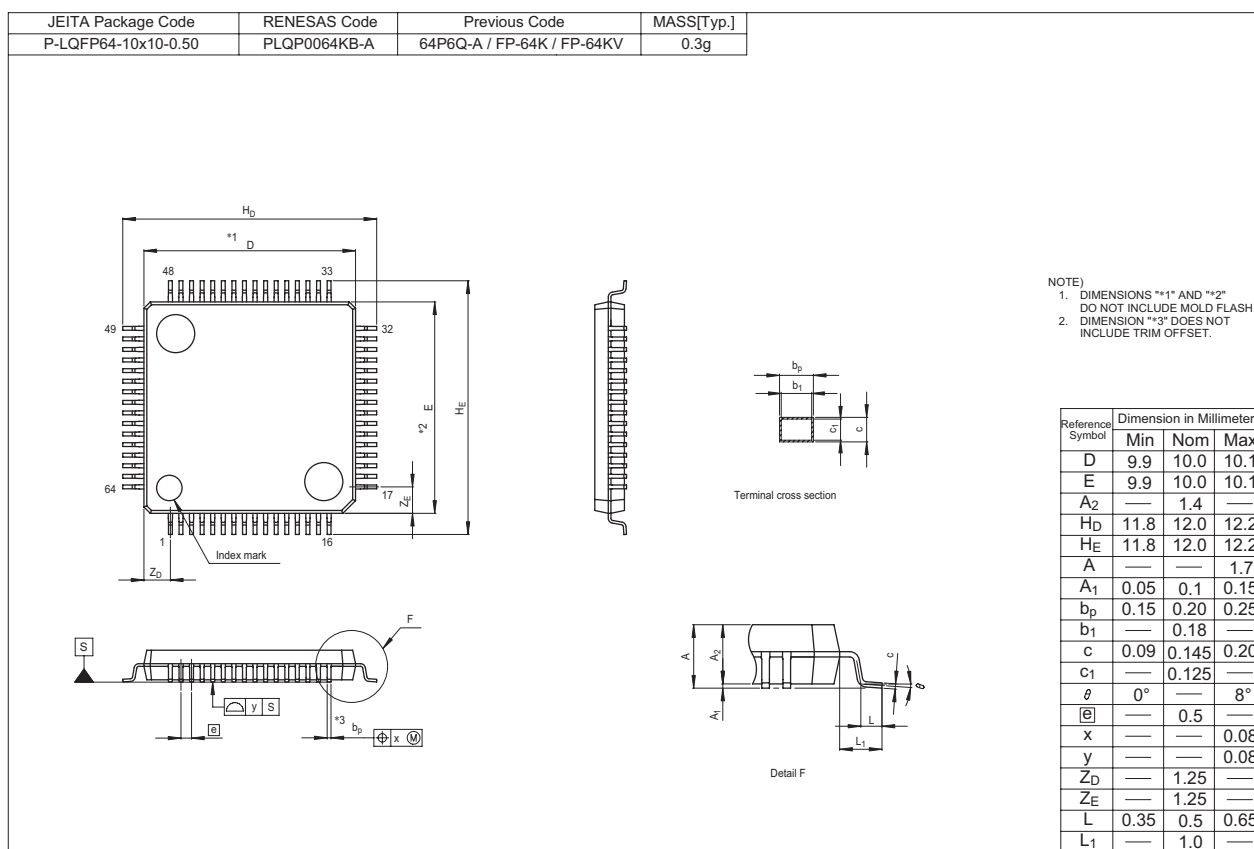
**Notes:**

1. When using timer RF input capture mode, adjust the cycle time to  $(1/\text{timer RF count source frequency} \times 3)$  or above.
2. When using timer RF input capture mode, adjust the pulse width to  $(1/\text{timer RF count source frequency} \times 1.5)$  or above.

**Figure 5.20 TRFI Input Timing Diagram when  $V_{CC} = 2.2\text{ V}$**

## Package Dimensions

Diagrams showing the latest package dimensions and mounting information are available in the “Packages” section of the Renesas Electronics website.



## General Precautions in the Handling of MPU/MCU Products

The following usage notes are applicable to all MPU/MCU products from Renesas. For detailed usage notes on the products covered by this manual, refer to the relevant sections of the manual. If the descriptions under General Precautions in the Handling of MPU/MCU Products and in the body of the manual differ from each other, the description in the body of the manual takes precedence.

### 1. Handling of Unused Pins

Handle unused pins in accord with the directions given under Handling of Unused Pins in the manual.

- The input pins of CMOS products are generally in the high-impedance state. In operation with an unused pin in the open-circuit state, extra electromagnetic noise is induced in the vicinity of LSI, an associated shoot-through current flows internally, and malfunctions occur due to the false recognition of the pin state as an input signal become possible. Unused pins should be handled as described under Handling of Unused Pins in the manual.

### 2. Processing at Power-on

The state of the product is undefined at the moment when power is supplied.

- The states of internal circuits in the LSI are indeterminate and the states of register settings and pins are undefined at the moment when power is supplied.

In a finished product where the reset signal is applied to the external reset pin, the states of pins are not guaranteed from the moment when power is supplied until the reset process is completed.

In a similar way, the states of pins in a product that is reset by an on-chip power-on reset function are not guaranteed from the moment when power is supplied until the power reaches the level at which resetting has been specified.

### 3. Prohibition of Access to Reserved Addresses

Access to reserved addresses is prohibited.

- The reserved addresses are provided for the possible future expansion of functions. Do not access these addresses; the correct operation of LSI is not guaranteed if they are accessed.

### 4. Clock Signals

After applying a reset, only release the reset line after the operating clock signal has become stable. When switching the clock signal during program execution, wait until the target clock signal has stabilized.

- When the clock signal is generated with an external resonator (or from an external oscillator) during a reset, ensure that the reset line is only released after full stabilization of the clock signal. Moreover, when switching to a clock signal produced with an external resonator (or by an external oscillator) while program execution is in progress, wait until the target clock signal is stable.

### 5. Differences between Products

Before changing from one product to another, i.e. to one with a different part number, confirm that the change will not lead to problems.

- The characteristics of MPU/MCU in the same group but having different part numbers may differ because of the differences in internal memory capacity and layout pattern. When changing to products of different part numbers, implement a system-evaluation test for each of the products.

## Notice

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